

PXD6 Technology status

22.9.2009

● Relevant process sequence

ALIN - Alignment marks

POXP - backside boron implant

Wafer bonding

Thermal Oxidation

Front/backside alignment

Global HE implantation (unmasked)

done

Nitride deposition

done

Polysilicon deposition

done

introduction of a polysilicon option

LTO deposition

done

Polysilicon doping (outside implantation)

Polysilicon annealing

PO1N polysilicon photolithography and etching

wet etching - plasma etch

Yield problem I - Polysilicon roughness

Poly I + II edges and surfaces

